

PTO/SB/17 (05-03)

Approved for use through 04/30/2003. OMB 0851-0032
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FEE TRANSMITTAL
for FY 2003

Effective 01/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27**TOTAL AMOUNT OF PAYMENT** (\$)**84.00****Complete if Known**

Application Number	10/045,354
Filing Date	November 7, 2001
First Named Inventor	Angela Hui et al.
Examiner Name	Khiem D. Nguyen
Art Unit	2823
Attorney Docket No.	AMDP714US

METHOD OF PAYMENT (check all that apply)
☐ Check ☐ Credit card ☐ Money Order ☒ Other ☐ None
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Deposit Account Number	50-1733
Deposit Account Name	ESCHWEILER & ASSOCIATES, LLC

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FEE CALCULATION**1. BASIC FILING FEE**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1001 750	2001 375	Utility filing fee	
1002 330	2002 165	Design filing fee	
1003 520	2003 260	Plant filing fee	
1004 750	2004 375	Reissue filing fee	
1005 180	2005 80	Provisional filing fee	
SUBTOTAL (1)			(\$) --

2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

Total Claims	Extra Claims	Fee below	Fee Paid
25	-26** =	18.00	
5	-4** =	84.00	84.00

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1202 18	2202 9	Claims in excess of 20	
1201 84	2201 42	Independent claims in excess of 3	
1203 280	2203 140	Multiple dependent claim, if not paid	
1204 84	2204 42	** Reissue independent claims over original patent	
1205 18	2205 9	** Reissue claims in excess of 20 and over original patent	
SUBTOTAL (2)			(\$) 84.00

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1051 130	2051 65	Surcharge - late filing fee or oath	
1052 50	2052 25	Surcharge - late provisional filing fee or cover sheet	
1053 130	1053 130	Non-English specification	
1812 2,520	1812 2,520	For filing a request for ex parte reexamination	
1804 920*	1804 920*	Requesting publication of SIR prior to Examiner action	
1805 1,840*	1805 1,840*	Requesting publication of SIR after Examiner action	
1251 110	2251 55	Extension for reply within first month	
1252 410	2252 205	Extension for reply within second month	
1253 930	2253 465	Extension for reply within third month	
1254 1,450	2254 725	Extension for reply within fourth month	
1255 1,970	2255 985	Extension for reply within fifth month	
1401 320	2401 160	Notice of Appeal	
1402 320	2402 160	Filing a brief in support of an appeal	
1403 280	2403 140	Request for oral hearing	
1451 1,510	1451 1,510	Petition to institute a public use proceeding	
1452 110	2452 55	Petition to revive - unavoidable	
1453 1,300	2453 650	Petition to revive - unintentional	
1501 1,300	2501 650	Utility issue fee (or reissue)	
1502 470	2502 235	Design issue fee	
1503 630	2503 315	Plant issue fee	
1460 130	1460 130	Petitions to the Commissioner	
1807 50	1807 50	Processing fee under 37 CFR 1.17(q)	
1808 180	1808 180	Submission of Information Disclosure Stmt	
8021 40	8021 40	Recording each patent assignment per property (times number of properties)	
1809 750	2809 375	Filing a submission after final rejection (37 CFR 1.129(a))	
1810 750	2810 375	For each additional invention to be examined (37 CFR 1.129(b))	
1801 750	2801 375	Request for Continued Examination (RCE)	
1802 900	1802 900	Request for expedited examination of a design application	

Other fee (specify)

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$)**--****SUBMITTED BY**Name (Print/Type) **Thomas J. Eschweiler**

Registration No. (Attorney/Agent)

36,981

(Complete if applicable)

Telephone **(216) 502-0600**

Signature

Date

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Paper No. 9

Dock t No. AMDP714USAF01159IN THE UNITED STATES PATENT AND TRADEMARK OFFICEIn re **PATENT** application of:

Applicant: Angela Hui, et al.
Application No.: 10/045,354
For: AN INNOVATIVE METHOD OF HARD MASK REMOVAL
Filing Date: November 7, 2001
Examiner: Khiem D Nguyen
Art Unit: 2823

#9/C
7/11/03
vsSUPPLEMENTAL REPLY TO OFFICE ACTION DATED APRIL 2, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Favorable reconsideration of the above-identified application is respectfully
requested in view of the following amendments and remarks.

AMENDMENTSIN THE CLAIMS:

Please amend claims 1, 19, 21 and 24, cancel claims 25-26, and add new claim
27 as follows below:

1. (Currently amended) A method of stripping a hard mask from a substrate comprising an insulating material exposed within gaps patterned through the hard mask, comprising:
- coating the substrate with a sacrificial material that fills the gaps; and
 - plasma etching to strip the sacrificial material and the hard mask substantially completely in a single plasma etch process.

Please enter the
amendments
in
Paper No. 9
K.D.N.
07/11/03